

Electronic Patent Application Fee Transmittal

Application Number:	10561577			
Filing Date:				
Title of Invention:	Device Comprising Circuit Elements Connected By Bonding Bump Structure			
First Named Inventor/Applicant Name:	Joseph Bellaiche			
Filer:	Aaron Waxler/Patti DeMichele			
Attorney Docket Number:	FR02 0116 US			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Processing Fee, except for Provis. apps	1808	1	130	130
Total in USD (\$)				130